

What is claimed is:

1. A heat spreader, comprising:
a body formed from heat conductive material; and
a plurality of standoffs formed on said body.
2. The heat spreader of claim 1, wherein the heat conductive material is further plated with nickel.
3. The heat spreader of claim 1, wherein the heat conductive material is further coated with heat-conductive organic material.
4. The heat spreader of claim 1, wherein the body has a plurality of mechanical attachment structures bonded to the surface.
5. A heat spreader, comprising:
a body formed from heat conductive material; and
a non-contiguous wall structure formed around the periphery of said body.
6. The heat spreader of claim 5, wherein the heat conductive material is further plated with nickel.

7. The heat spreader of claim 5 wherein the heat conductive material is coated with a heat-conductive organic material.
8. A heat spreader, comprising:
 - a body formed from heat conductive material;
 - a wall structure formed around the periphery of said body; and
 - a plurality of standoffs formed on the inside surface of said body.
9. The heat spreader of claim 8, wherein the wall structure is non-contiguous.
10. The heat spreader of claim 9, wherein the heat conductive material is further plated with nickel.
11. The heat spreader of claim 9, wherein the heat conductive material is coated with a heat-conductive organic material.
12. A heat spreader, comprising:
 - a body formed from heat-conductive material; and
 - a pedestal formed on said body.

13. The heat spreader of claim 12, wherein the heat conductive material is further plated with nickel.

14. The heat spreader of claim 12, wherein the heat conductive material is coated with heat-conductive organic material.

15. A heat spreader, comprising:
a body formed from heat-conductive material;
a wall structure on the periphery of said body; and
a pedestal formed on said body.

16. The heat spreader of claim 15, wherein the heat conductive material is further plated with nickel.

17. The heat spreader of claim 15, wherein the heat conductive material is coated with a heat-conductive organic material.

18. A semiconductor package, comprising:
a substrate having a top surface;
at least one semiconductor device attached to said top surface of said substrate;

a cover secured to said substrate creating a space therebetween, said semiconductor device residing within said space, said cover having a flat top surface with standoffs attached thereon and an external bottom surface; and said cover further comprised of a heat conductive material.

19. The semiconductor package of claim 18, wherein the cover is a heat spreader.
20. The semiconductor package of claim 19, wherein the cover is attached to the substrate using polymeric sealant material.
21. The semiconductor package of claim 20, wherein the cover has mechanical attachment structures bonded to the surface.
22. The semiconductor package of claim 18, wherein the heat spreader is attached to the substrate using a wall structure.
22. The semiconductor package of claim 18, wherein the flat top surface has a pedestal.